

KT33813UG

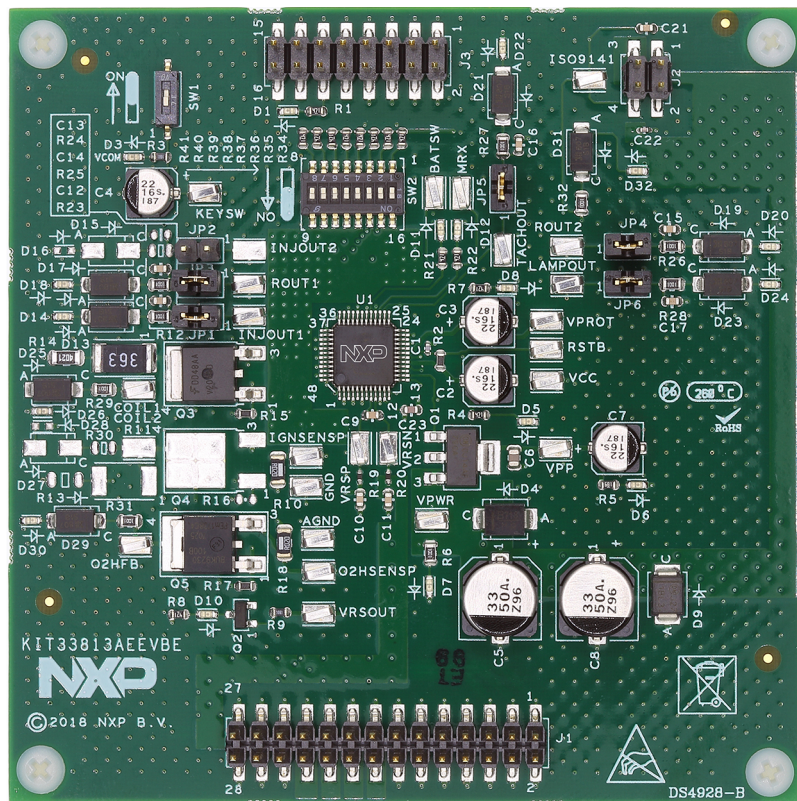
KIT33813AEEVBE evaluation board

Rev. 3.0 — 2 October 2018

User guide

KIT33813AEEVBE

The KIT33813AEEVBE board is an easy-to-use circuit board that allows the user to exercise all the functions of the MC33813 one cylinder small engine control IC. A PC communicates to the evaluation board through a USB/SPI Dongle (KITUSBPIDGLEVME) connected to the PC's USB port. The NXP SPIGen (version 7.1.8) program provides the user interface to the MC33813 SPI port and allows the user to send commands to the IC and receive status from the IC.



aaa-031704



1 Finding kit resources and information on the NXP web site

NXP Semiconductors provides online resources for this evaluation board and its supported device(s) on <http://www.nxp.com>.

The information page for KIT33813AEEVBE evaluation board is at <http://www.nxp.com/KIT33813AEEVBE>. The information page provides overview information, documentation, software and tools, parametrics, ordering information and a **Getting Started** tab. The **Getting Started** tab provides quick-reference information applicable to using the KIT33813AEEVBE evaluation board, including the downloadable assets referenced in this document.

1.1 Collaborate in the NXP community

The NXP community is for sharing ideas and tips, ask and answer technical questions, and receive input on just about any embedded design topic.

The NXP community is at <http://community.nxp.com>.

2 Getting ready

Working with the KIT33813AEEVBE requires the kit contents, additional hardware and a Windows PC workstation with installed software.

2.1 Kit contents

- Assembled and tested KIT33813AEEVBE board in an anti-static bag

2.2 Additional hardware

In addition to the kit contents, the following hardware is necessary or beneficial when working with this kit.

- Power supply 12 V with current limit set initially to 1.0 A
- Oscilloscope (4 channel preferably) with current probe
- Multimeter
- USB/SPI Dongle board (KITUSBSPIDGLEVME) plus 16-pin ribbon cable
- Typical loads (DC servo motor, fuel injectors, solenoids, lamps, relays and tachometer)

2.3 Windows PC workstation

This evaluation board requires a Windows PC workstation. Meeting these minimum specifications should produce great results when working with this evaluation board.

- USB-enabled computer with Windows XP or higher

2.4 Software

Installing software is necessary to work with this evaluation board. All listed software is available on the evaluation board's information page at <http://www.nxp.com/KIT33813AEEVBE>.

- SPI Generator (SPIGen) software, version 7.1.8 or later

3 Getting to know the hardware

The NXP analog product development boards provide an easy-to-use platform for evaluating NXP products. The boards support a range of analog, mixed-signal and power solutions. They incorporate monolithic integrated circuits and system-in-package devices that use proven high-volume technology. NXP products offer longer battery life, a smaller form factor, reduced component counts, lower cost and improved performance in powering state-of-the-art systems.

3.1 Kit overview

3.1.1 KIT33813AEEVBE features

This evaluation board consists of a MC33813 one cylinder small engine control IC, a USB to SPI Dongle interface, and power conditioning circuitry. All +5.0 V VCC power required by the board is obtained from the MC33813 built-in power regulator. A +12 V VBAT supply provides the power to the three internal voltage regulators.

3.1.2 KIT33813AEEVBE block diagram

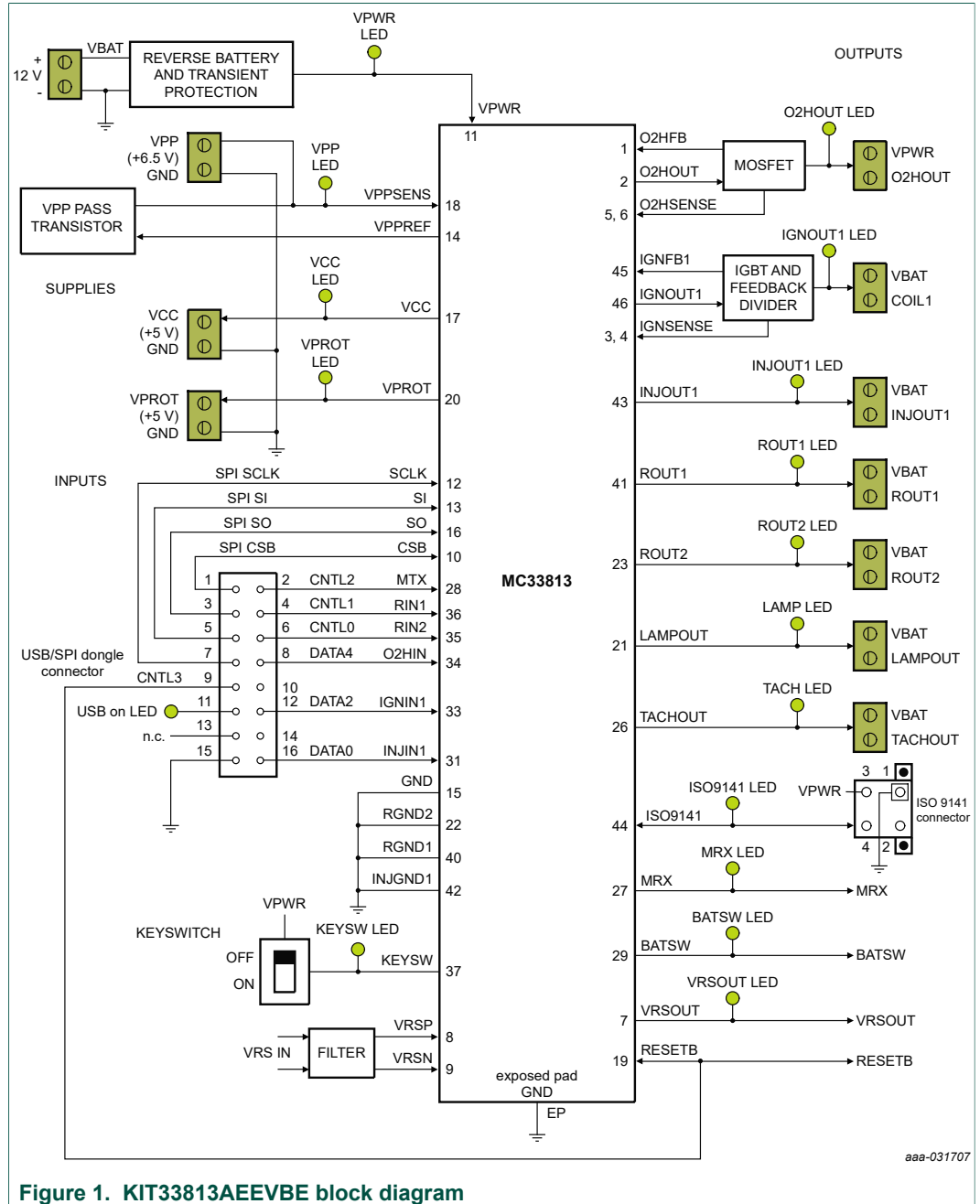


Figure 1. KIT33813AEEVBE block diagram

3.1.3 Schematic, board layout and bill of materials

The schematic, board layout and bill of materials for the KIT33813AEEVBE are available at <http://www.nxp.com/KIT33813AEEVBE>.

3.2 Featured components

Figure 2 identifies important components on the KIT33813AEEVBE board and Table 1 provides additional details on these components.

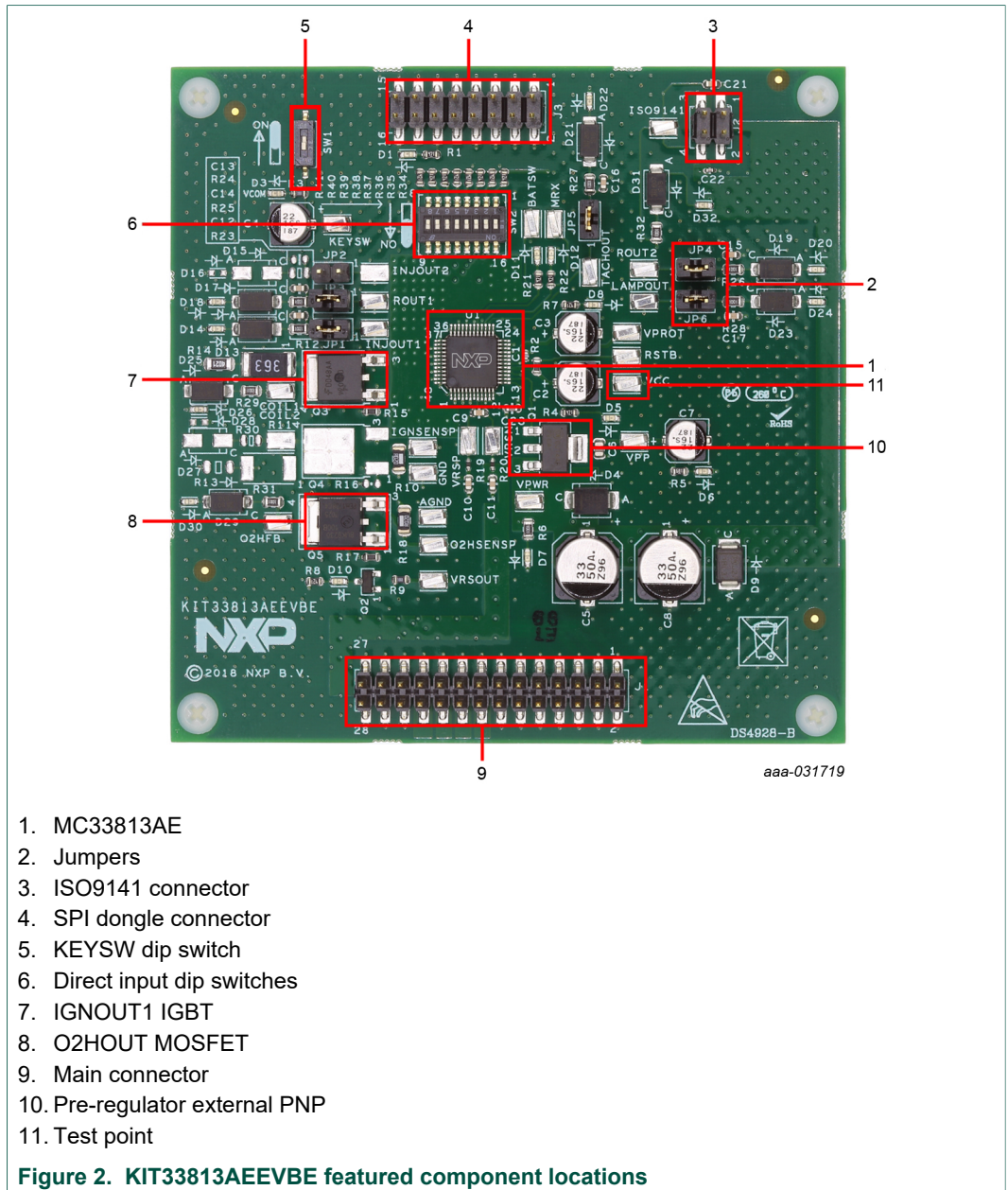


Table 1. KIT33813AEEVBE board component descriptions

| Name | Description |
|---------------------------|---|
| MC33813AE | one cylinder small engine control IC |
| Jumpers | used to disconnect LSD from loads to experience open load functionality |
| ISO9141 connector | connection to K-line transceiver |
| SPI dongle connector | compatible with USB/SPI dongle |
| KEYSW dip switch | used to wake the device up |
| Direct input dip switches | when no USB/SPI is connected, direct accesses to LSD and predriver inputs |
| IGNOUT1 IGBT | drives an ignition coil |
| O2HOUT MOSFET | can drive an O2 heater sensor |
| Main connector | connection to battery, GND, external loads and VRS |
| Test point | to probe different signals |

3.2.1 MC33813: One cylinder small engine control IC

3.2.1.1 General description

Powered by SMARTMOS technology, the 33813 delivers a cost-optimized IC solution for managing one-cylinder engines. With five drivers, two pre-drivers, a 5.0 V regulator for the MCU, a protected external sensor supply and a high level of integration, the IC offers an ideal response to contemporary market requirements.

The innovative VRS system optimizes noise immunity under cranking conditions. Diagnostic and protection features present on all outputs allow applications to operate with greater safety.

3.2.1.2 Features

The MC33813 is an engine control analog power IC intended for one cylinder motorcycle and other small engine control applications. The device supports the following functionality:

- One fuel injector driver typical of 1.3 A
- One ignition IGBT or general purpose gate predriver
- One O2 sensor (HEGO) heater general purpose gate predriver
- Relay 1 driver, typically 2.0 A, can be used for fuel pump control
- Relay 2 driver, typically 1.0 A, can be used as power relay control
- Lamp driver, typically 1.0 A can also be used to drive an LED
- Independent fault protection with all faults reported via the SPI
- ISO 9141 K-line interface for communicating diagnostic messages
- Start-up/shutdown control and power sequence logic
- Interfaces directly to MCU using a 5.0 V SPI and logic I/O
- Differential/single-ended VRS conditioning circuit

3.3 Indicators

The following 17 LEDs are provided as visual output devices for the evaluation board:

Table 2. KIT33813AEEVBE indicator descriptions

| Label | Description |
|---------|--|
| VPWR | indicates when +12 V supply is connected to the evaluation board |
| VPP | indicates that the VPP pre-regulator is supplying +6.5 V to the two +5 V regulators, VCC and VPROT |
| VCC | indicates that the MC33813 internal +5 V regulator is running and providing the +5 V VCC voltage supply |
| VPROT | indicates that the VPROT +5 V regulator is turned ON and is supplying 5.0 V |
| KEYSW | indicates when the key switch is turned ON supplying +12 V to the KEYSW input |
| IGNOUT1 | indicates that the ignition input, IGNIN1 or SPI bit, is active and the ignition 1 output driver is turned ON |
| O2HOUT | indicates that the O2HIN input or the SPI bit is active and the O2 heater driver output is turned ON |
| INJOUT1 | indicates that the injector 1 input, INJIN1 or SPI bit, is active and the Injector 1 output is pulled low |
| ROUT1 | indicates that the relay 1 input RIN1, or SPI bit, is active and the relay 1 output is pulled low |
| ROUT2 | indicates that the relay 2 input RIN2, or SPI bit, is active and the relay 2 output is pulled low |
| LAMPOUT | indicates that the lamp SPI control bit is active and the LAMPOUT pin is pulled low |
| VRSOUT | indicates that there is activity on the VRSN and VRSP pins and that the VRS circuit has detected a valid VRS signal |
| TACHOUT | indicates the state of the TACHOUT output signal |
| MRX | indicates the state of the MRX line as a result of the data on the ISO9141 line |
| BATSW | indicates the state of the on-board key switch. When the key switch is ON, the BATSW LED is ON. |
| USB | indicates that the USB SPI dongle is connected properly and is attached to an active USB port on a PC |
| ISO9141 | indicates the state of the ISO9141 line. When this LED is ON, the ISO9141 line is low and when the LED is OFF, the ISO9141 line is high. |

3.4 Test points

The board contains 23 test point jumpers that provide access to various signals to and from the board.

Table 3. KIT33813AEEVBE test point descriptions

| Test point name | Description |
|-----------------|---|
| VPWR | 12 V (VBAT minus Schottky diode drop) |
| GND | 0 V |
| VPP | 6.5 V |
| VCC | 5.0 V |
| VPROT | 5.0 V |
| BATSW | 0 or 5.0 V depending on the state of KEYSW |
| KEYSW | 0 or 12 V depending on the state of KEYSW |
| ISO9141 | 0 or 12 V depending on the state of MTX |
| MRX | 0 or 5 V depending on the state of ISO9141 line |
| VRSOUT | 0 or 5 V depending on the VRSN and VRSP inputs |

| Test point name | Description |
|-----------------|--|
| TACHOUT | 0 or 5 V depending on VRSOUT or internal SPI bits |
| LAMPOUT | 0 or 12 V depending on the SPI bits |
| ROUT2 | 0 or 12 V depending on RIN2 or internal SPI bits |
| ROUT1 | 0 or 12 V depending on RIN1 or internal SPI bits |
| INJOUT1 | 0 or 12 V depending on INJIN1 or internal SPI bits |
| COIL1 | 0 or 12 V depending on IGNIN1 or internal SPI bits |
| O2HFB | 0 or 12 V depending on O2HOUT or internal SPI bits |
| VRSN | -0.3 to 5 V (clamped internally) from VRS low-side |
| VRSP | -0.3 to 5 V (clamped internally) from VRS high-side |
| O2HSENSN | Ground side of O2H driver current sense resistor (.02 ohms) |
| O2HSENSP | High-side of O2H driver current sense resistor (.02 ohms) |
| IGNSENSN | Ground side of IGN1/2 driver current sense resistor (.02 ohms) |
| IGNSENSP | High-side of IGN1/2 driver current sense resistor (.02 ohms) |

3.5 Input signal definitions

The following seven input signals control the outputs or functions inside the circuit.

Table 4. Input signal definitions

| Input name | Description |
|------------|--|
| O2HIN | controls the O2 heater predriver output |
| IGNIN1 | controls the ignition 1 predriver output |
| INJIN1 | controls the state of the INJOUT1 output |
| RIN1 | controls the state of the ROUT1 output |
| RIN2 | controls the state of the ROUT2 output |
| MTX | provides the transmit data to the ISO9141 line |
| RESETB | when the RESETB line is held low, the MC33813 inhibits the internal watchdog reset |

The following signals are provided by the seven parallel outputs from the USB/SPI interface.

Table 5. USB/SPI direct control outputs connections

| Input name | Description |
|------------|-------------------------------|
| O2HIN | connected to the DATA4 signal |
| IGNIN1 | connected to the DATA2 signal |
| INJIN1 | connected to the DATA0 signal |
| RIN1 | connected to the CNTL1 signal |
| RIN2 | connected to the CNTL0 signal |
| MTX | connected to the CNTL2 signal |
| RESETB | connected to the CNTL3 signal |

DATA0-DATA4 and CNTL0-CNTL3 signals are logic level outputs from the USB/SPI Dongle that can be controlled directly from the SPIGen program. An example SPIGEN configuration file called KIT33813SW.spi is provided in the software bundle which contains several batch file examples.

If the user prefers to supply the various MC33813 input signals externally other than from the USB-SPI interface, the dip switch SW2 can be used with the following:

- 1: not used
- 2: RIN1
- 3: RIN2
- 4: O2HIN
- 5: not used
- 6: IGNIN1
- 7: not used
- 8: INJIN1

3.6 USB/SPI dongle connector

The USB/SPI dongle connector is a 16-pin, .1" center, dual-row connector that is designed to interface directly to the USB/SPI Dongle unit (KITUSBSPIDGLEVME). This connector mates with the 16-conductor flat cable that connects to the USB/SPI Dongle. The USB/SPI dongle connector consists of the following 16 pins.

Table 6. USB/SPI dongle pin description

| Pin number | Name | Description |
|------------|-------|---|
| 1 | CNTL2 | CNTL2 connected to MTX |
| 2 | CSB | SPI signal, chip select bar |
| 3 | CNTL1 | CNTL1 connected to RIN1 |
| 4 | SO | SPI signal, serial out |
| 5 | CNTL0 | CNTL0 connected to RIN2 |
| 6 | SI | SPI signal, serial in |
| 7 | DATA4 | DATA4 connected to O2HIN |
| 8 | SCLK | SPI signal, serial clock |
| 10 | DATA3 | n.c. |
| 11 | DATA2 | DATA2 connected to IGNIN1 |
| 12 | VDD | +5.0 V VDD from USB |
| 13 | DATA1 | n.c. |
| 14 | +3.3V | +3.3 V from USB (not used on this evaluation board) |
| 15 | DATA0 | DATA0 connected to INJIN1 |
| 16 | GND | Signal ground |

3.7 Screw terminal connections

The MC33813 board contains ten output and two input screw terminal connections and one 4 pin I/O connector to allow easy access to the MC33813's circuits.

[Figure 3](#) shows the locations of the screw terminals.

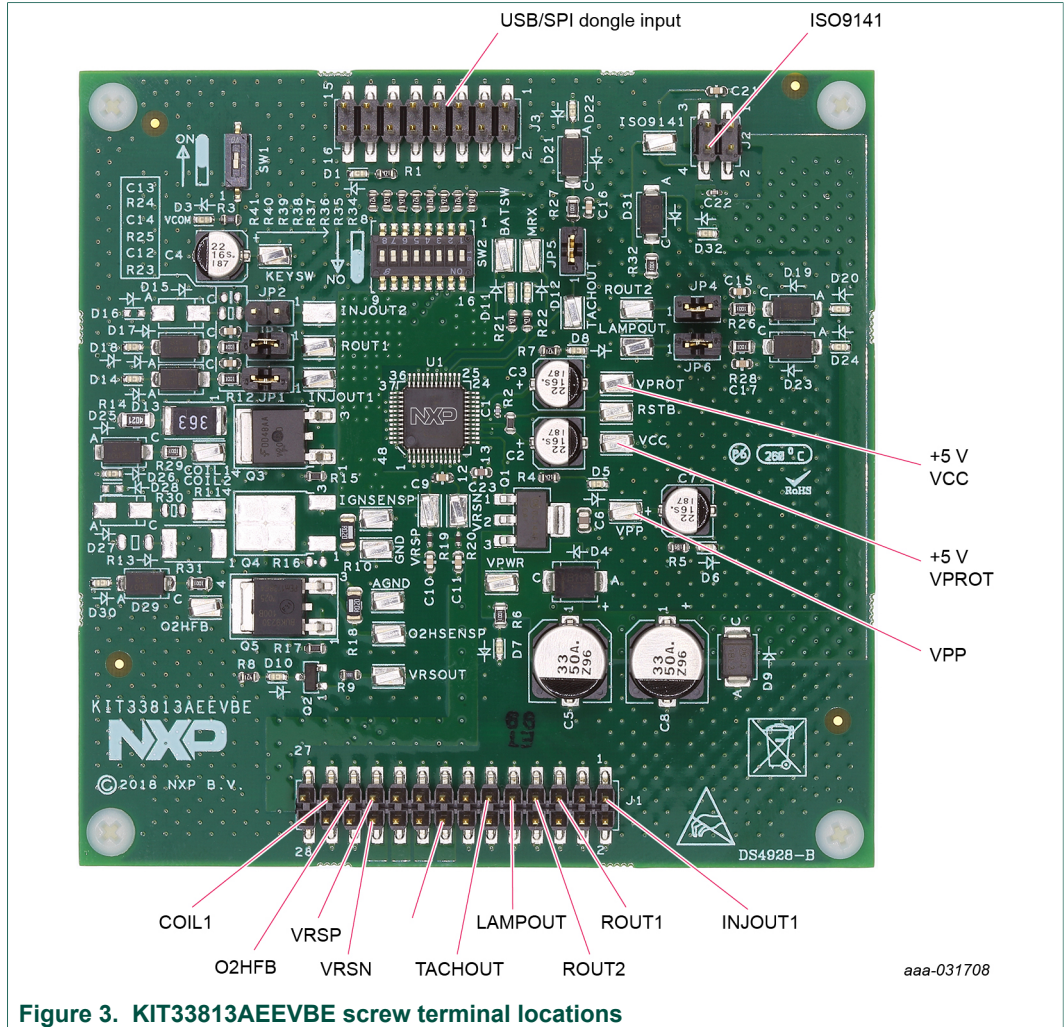


Figure 3. KIT33813AEEVBE screw terminal locations

3.8 Board connectors

Table 7. Main connector

| Label | Pin numbers on main connector (J1) |
|---------|------------------------------------|
| INJOUT1 | 1 |
| ROUT1 | 5 |
| ROUT2 | 7 |
| LAMPOUT | 9 |
| TACHOUT | 11 |
| VBAT | 2, 4, 6, 8, 10, 12, 14, 24, 26, 28 |
| GND | 13, 15, 17, 19 |
| VRSP | 21 |
| O2HFB | 23 |
| COIL1 | 25 |
| VCC | 16 |
| VPROT | 18 |

| Label | Pin numbers on main connector (J1) |
|-------|------------------------------------|
| VPP | 20 |
| VRSN | 22 |

Table 8. ISO9141 connector

| Label | Pin numbers on ISO9141 connector (J2) |
|---------|---------------------------------------|
| GND | 1 |
| VPWR | 3 |
| ISO9141 | 4 |

3.9 SPI dongle connector (J3)

Table 9. SPI dongle connector

| Label | Pin numbers on USB/SPI connector (J3) |
|--------|---------------------------------------|
| MTX | 1 |
| CSB | 2 |
| RIN1 | 3 |
| SO | 4 |
| RIN2 | 5 |
| SI | 6 |
| O2HIN | 7 |
| SCLK | 8 |
| IGNIN1 | 11 |
| +5V | 12 |
| INJIN1 | 15 |
| GND | 16 |

4 Accessory board

The KITUSBSPIDGLEVME evaluation board provides a USB to SPI interface that features the MC68HC908JW32 with Dongle. It is a working hardware/software example that allows a user to become familiar with the MC68HC908JW32 microcontroller by means of an actual useful application, a USB to SPI and USB to parallel converter.

The main function provided by this kit is to allow a PC, that may not have a parallel port, to communicate with other NXP evaluation kits, via a USB port. The USB port is a standard feature on almost every new PC. This kit makes use of the MC68HC908JW32's built-in USB, SPI and parallel ports.



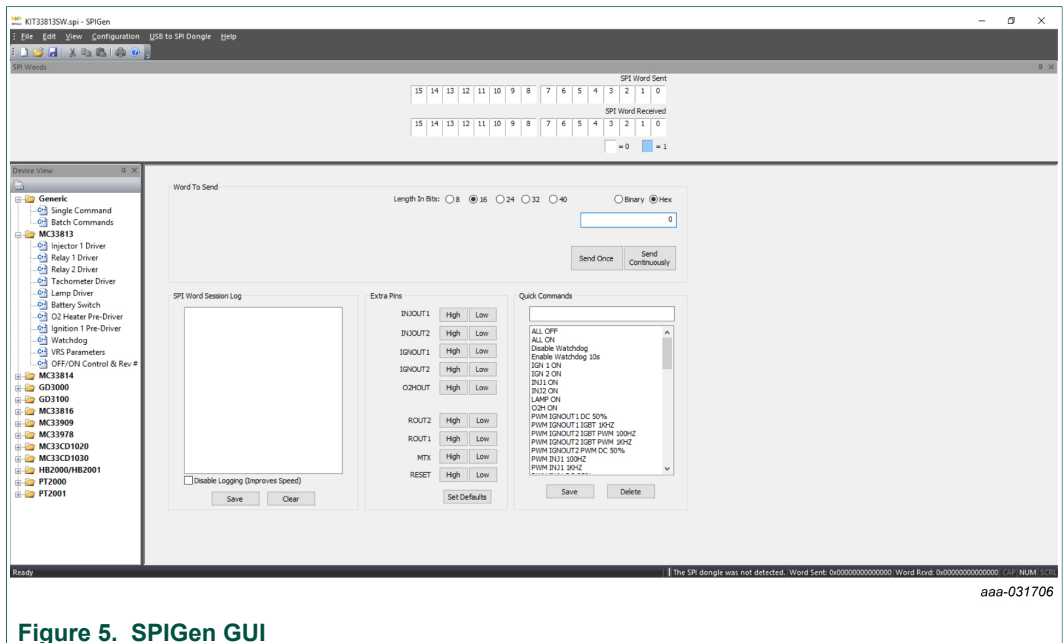
5 Installing and configuring software and tools

5.1 Installing SPIGen on your computer

The latest version of SPIGen supports the MC33813 and is designed to run on any Windows 10, Windows 8, or Windows 7-based operating system. To install the software, do the following:

1. Go to www.nxp.com/SPIGen and click **Download**.
2. When the SPIGEN: SPI Generator (SPIGen) software page appears, go to the **Lab and Test Software** section and click **Download** associated with the description of the selected environment. A wizard guides the user through the process.
3. If instructed for the SPIGen wizard to create a shortcut, a SPIGen icon appears on the desktop. By default, the SPIGen executable file is installed at **C:\Program Files (x86)\SPIGen**.

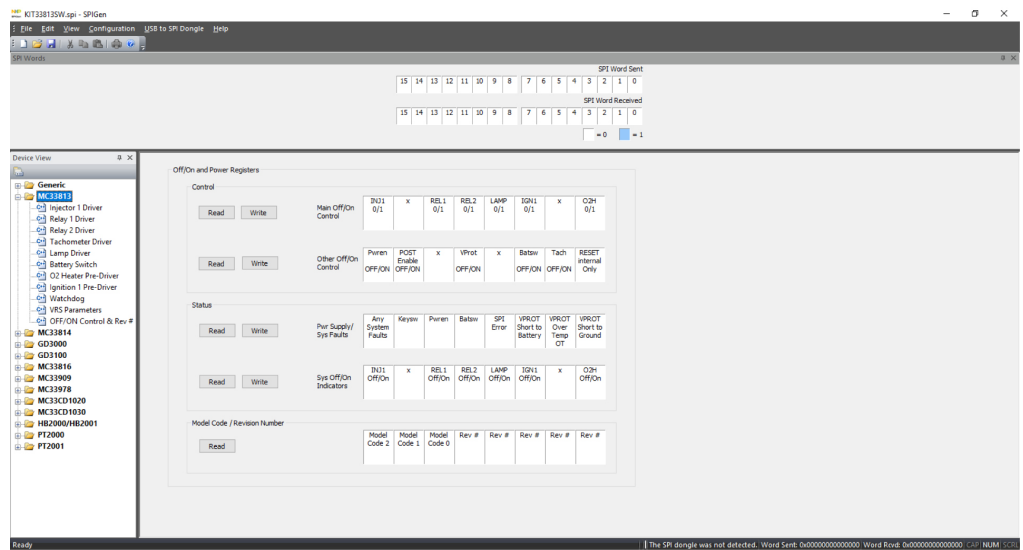
Installing the device drivers overwrites any previous SPIGen installation and replaces it with a current version containing the MC33813 drivers. However, configuration files (.spi) from the previous version remain intact.



The GUI is shown in [Figure 5](#). The text at the top is the name of the configuration file loaded. The left side panel displays folders that group user interfaces. The interfaces in the pre-installed MC33813 folder pertain specifically to the board under discussion. Loading a specific configuration file, allows you to add a list of **Extra Pins** as well as a list of **Quick Commands**.

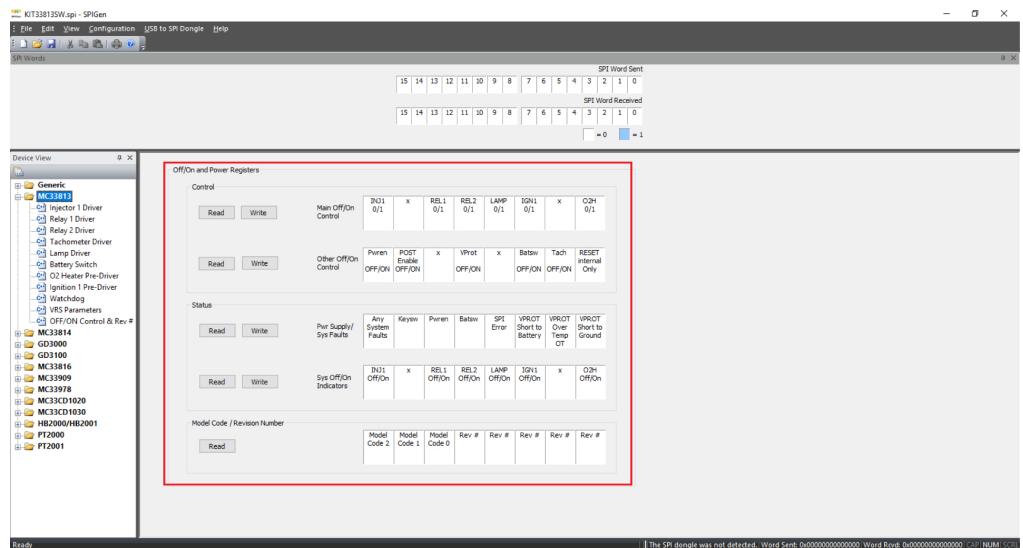
5.2 Using SPIGen graphical user interface

1. Launch SPIGen. The MC33813 device appears in the **Device View** panel.



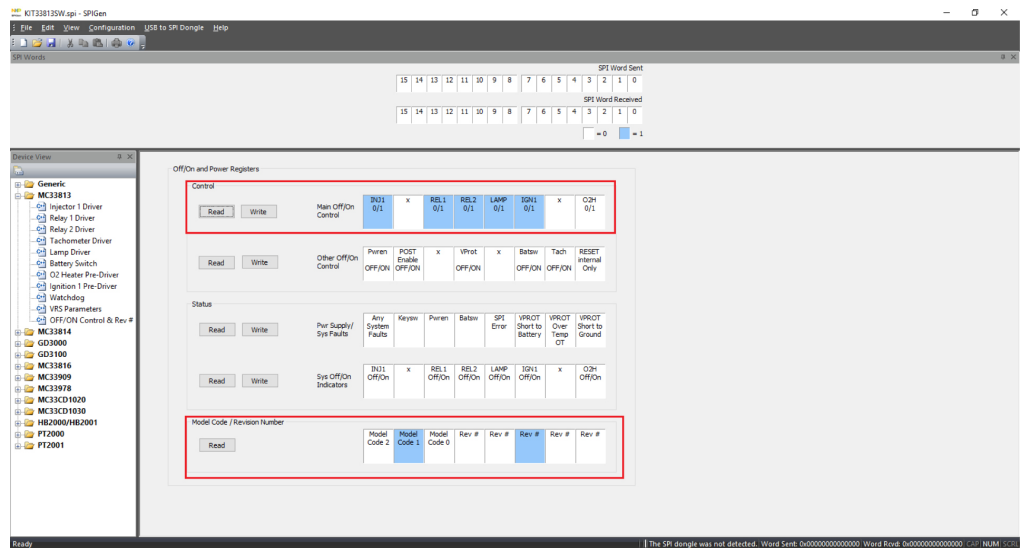
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2. The registers can be accessed by choosing one register icon.



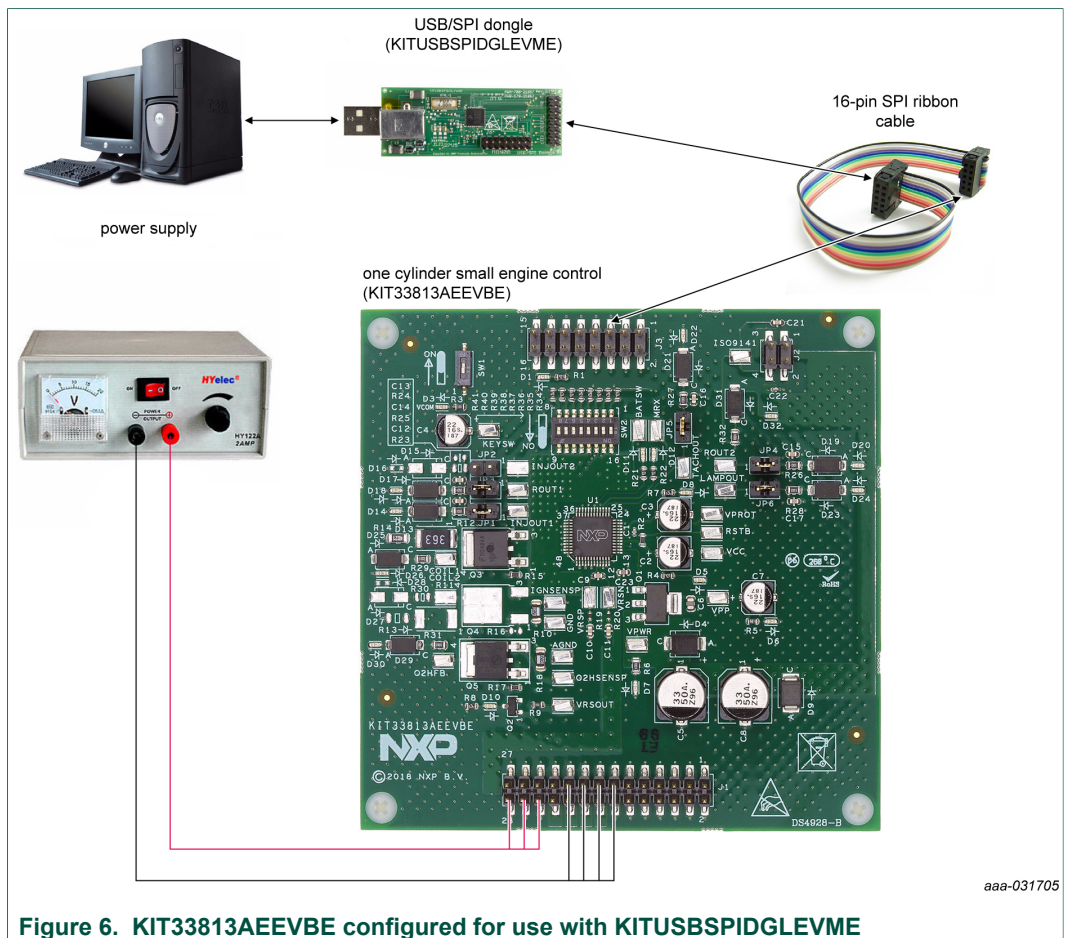
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3. Reading the Model Code/Revision Number displays the following values. In the same tab, the LSD, and predrivers can be switched ON and OFF through SPI.



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6 Configuring the hardware



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Figure 6. KIT33813AEEVBE configured for use with KITUSBSPIDGLEVME

To perform the examples included in the software bundle, the following connections and setup must be performed:

1. Make sure the SPIGen (version 7.1.8 or greater) program is installed on the PC and it can communicate with the USB/SPI Dongle.
2. Connect the USB/SPI Dongle to the MC33813 evaluation board via a 16-pin ribbon cable. Make sure to orient the cable so that pin1 on both the USB/SPI Dongle and the MC33813 evaluation board are connected correctly, pin 1 to pin 1.
3. Connect the USB/SPI Dongle to a PC, LED 2 on the USB/SPI Dongle and the USB ON LED on the MC33813 board should both be illuminated.
4. Attach a +12 VDC supply (do not turn on power yet) to the VBAT input connector on the MC33813 evaluation board, making sure to observe the GND and +12 V terminals. The current capability of the +12 V supply should exceed the maximum total current that the number of simultaneously ON loads require.
5. Attach loads to the COIL1, O2HFB, INJOUT1, ROUT1, ROUT2, LAMP OUT, TACHOUT and ISO9141 output terminals as desired.
6. Launch SPIGen and from the **File** menu, select **Open** and browse to the location of the **KIT33813SW.spi** file.
7. Turn on the +12 V supply and set the KEYSW slide switch to the DOWN position. Verify that all is working correctly by observing the VPWR, VPP, VCC and VPROT LEDs which should all be illuminated. Click the **Extra Pins** button in the main SPIGen screen and then click the following buttons:
 - a. Click **INJIN1 High**. The INJECTOR 1 load, INJOUT1, and LED should turn ON. Clicking **INJIN1 Low** should turn OFF the load and LED.
 - b. Click **RIN1 High**. The RELAY 1 load, ROUT1 and LED should turn ON. Clicking **RIN1 Low** should turn OFF the RELAY 1 load, ROUT1 and LED.
 - c. Click **RIN2 High**. The RELAY 2 load, ROUT2, and LED should turn ON. Clicking **RIN2 Low** button should turn OFF the RELAY 2 load, ROUT2 and LED.
 - d. Click **IGNIN1 High** button. The COIL1 load and LED should turn ON. Clicking **IGNIN1 Low** should turn OFF the COIL1 load and LED.
 - e. Click **O2HIN High** button. The O2 heater, O2HFB load and LED should turn ON. Clicking **O2HIN Low** should turn OFF the O2HFB load and LED.
 - f. Click **Data 3 High** button. The LAMP load and LED should turn ON. Clicking **Data 3 Low** should turn OFF the LAMP load and LED.
 - g. Click **Data 4 High**. The ISO9141 load should turn ON. Clicking **Data 3 Low** should turn OFF the ISO9141 load.

If everything described so far occurs, then you are ready to proceed with the remaining examples.

6.1 Example 1: running the example batch files

1. Click on the **Batch Commands** tab in the SPIGen main screen.
2. In the box below the Commands to Send: column is a pull-down menu containing several batch file names. One of these example batch files is labeled **TOGGLE ALL OUTPUTS**.
3. Click on this label to load it. You should see a list of commands in the **Command to Send** box.
4. Click **Continuous** and observe that the loads and LEDs attached to the MC33813 evaluation board are blinking ON and then going out in succession.

There are other demo batch examples that can be run and examined for learning how to use the evaluation board.

7 References

- [1] **KIT33813AEEVBE** — detailed information on this board, including documentation, downloads, and software and tools
<http://www.nxp.com/KIT33813AEEVBE>
- [2] **One cylinder small engine control IC** — product information on One cylinder small engine control IC, MC33813
<http://www.nxp.com/MC33813>
- [3] **SPIGen** — SPI generator software
<http://www.nxp.com/SPIGEN>

8 Revision history

Revision history

| Rev | Date | Description |
|-----|----------|---|
| v.1 | 20121211 | <ul style="list-style-type: none">• Initial version |
| v.2 | 20130409 | <ul style="list-style-type: none">• Added Jump Start link for downloading software and/or documents• Updated SPIGen section to match latest template |
| v.3 | 20181002 | <ul style="list-style-type: none">• The format of this document has been redesigned to comply with the new identity guidelines of NXP Semiconductors.• Legal texts have been adapted to the new company name where appropriate.• Added Section 3.9 and Section 5.2• Section 6: updated Figure 6• Section 3.4 and Section 3.8: updated• Section 3.6: updated Table 6• Section 3.7: updated Figure 3• Schematic, board layout, bill of material: replaced by Section 3.1.3 |

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